



Material Content Data Sheet



Sales Product Name		BSC028N06NS		Issued		15. June 2015			
MA#		MA001014854							
Package		PG-TDSON-8-7		Weight*		118.75 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	0.837	0.70	0.70	7047	7047	
leadframe	non noble metal	iron	7439-89-6	0.038	0.03		318		
	inorganic material	phosphorus	7723-14-0	0.011	0.01		96		
	non noble metal	copper	7440-50-8	37.762	31.80	31.84	317999	318413	
wire	noble metal	gold	7440-57-5	0.045	0.04	0.04	377	377	
encapsulation	organic material	carbon black	1333-86-4	0.087	0.07		733		
	plastics	epoxy resin	-	6.183	5.21		52067		
	inorganic material	silicondioxide	60676-86-0	37.271	31.39	36.67	313868	366668	
leadfinish	non noble metal	tin	7440-31-5	1.470	1.24	1.24	12378	12378	
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1394	1394	
solder	noble metal	silver	7440-22-4	0.031	0.03		258		
	non noble metal	tin	7440-31-5	0.024	0.02		206		
	non noble metal	lead	7439-92-1	1.168	0.98	1.03	9839	10303	
heatspreader	non noble metal	iron	7439-89-6	0.011	0.01		95		
	inorganic material	phosphorus	7723-14-0	0.003	0.00		29		
	non noble metal	copper	7440-50-8	11.320	9.53	9.54	95329	95453	
heat sink CLIP	non noble metal	iron	7439-89-6	0.022	0.02		188		
	inorganic material	phosphorus	7723-14-0	0.007	0.01		56		
	non noble metal	copper	7440-50-8	22.292	18.77	18.80	187723	187967	
*deviation	< 10%					Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com